

NEWS FROM IPC

New IPC Report Details How PCB Manufacturers Meet Today's Technology Demands

PCB Technology Trends 2014, a global biennial study published this month by IPC is now available. The survey-based study shows how PCB manufacturers are meeting today's technology demands and looks at the changes expected by 2019 that will affect PCB fabricators and their suppliers of materials and equipment.

Based on data collected from 132 companies worldwide, the 175-page PCB technology trends study presents the aggregate data segmented by application for five key segments: computers and telecommunications, consumer electronics, industrial and automotive electronics, medical electronics, and military and aerospace electronics.

The study covers such issues as: clock speed, heat dissipation, operation cycles, product life expectancy, environmental operating range, lamination cycles, board thickness, layer counts, line width and spacing, via diameters, aspect ratios, use of embedded technologies, surface-mount land dimensions, I/O pitch, test density, recyclable content, component size, and numbers of leads, solder joints and components per board area.

Among the many interesting findings, the study reports that nearly half of the responding PCB manufacturers for computer and telecommunications applications expect their highest clock speeds in 2019 to exceed 25 gigahertz. This segment had the highest clock speed predictions. The military and aerospace segment reported that heat dissipation is a design-limiting factor in half of their devices currently, which is the highest of the five applications studied, and they expect that percentage to rise in the next four years. More than one-third of responding companies in the military and aerospace segment are currently embedding passive components in their boards. Embedding of

passive and active components is expected to increase substantially by 2019 for all five applications studied.

PCB Technology Trends 2014 is available free to companies that participated in the survey. Other companies may purchase the report by visiting IPC's online store. The price for IPC members is \$675 and \$1,350 for non-members. For more information or to purchase the report, visit www.ipc.org/pcb-tech-trends-2014.

SUBMIT A PAPER AT IPC EXPO 2016

Submit an abstract for one of the industry's premier technical conferences or provide a course proposal for one of its largest educational events.

Presenting at IPC APEX EXPO 2016 in Las Vegas will provide significant visibility for you and your organization. Thousands of individuals will receive the technical proceedings from this event, ensuring that your material will be seen by key managers and executives from all segments of the worldwide electronics industry. Presenting a technical conference paper or teaching a professional development course is a unique and cost-effective channel to promote your expertise and your organization to your customers and prospects.

TOPICS for Technical Conference Papers and Professional Development Courses

Submissions are sought on design, materials, assembly, processes and equipment in areas from adhesives and advanced technology to underfills and via plugging.

TECHNICAL CONFERENCE REQUIREMENTS FOR SUBMISSION

Provide an abstract of approximately 300 words that summarizes technical work, covering case histories, research and discoveries. It must be received by **August 14, 2015**. Authors of papers selected for the conference will each receive a detailed speaker manual to assist them with numerous items, including the formatting of their papers and presentation slides.

The selection process is competitive and sufficient detail needs to be included to allow the Technical Program Committee to properly assess

content of the proposed paper. If your abstract is selected, your paper will be due **November 13, 2015** and presentation slides will be due on **December 11, 2015**. The paper should be non-commercial and describe significant results from experiments, emphasize new techniques, discuss trends of interest and contain technical and/or appropriate test results. Presentations will be limited to 30 minutes, including 5–10 minutes for questions and answers.

SPEAKER BENEFITS

Conference speakers are entitled to a free one-day conference pass for the day of their presentations, discounted registration fees for the full conference and complimentary admission to the exhibit hall. All speakers selected for papers who also provide their presentations to IPC by **November 13, 2015** will be eligible for a free full-conference pass.

SPEAKER RECOGNITION AWARDS

To recognize exceptional achievement, an award for “Best Paper” will be presented which consists of a recognition plaque and a \$1,000 prize. Co-authors share the honorarium, but all will receive individual recognition plaques.

PLEASE NOTE

Previously published papers and/or commercially-focused papers are not appropriate and will not be accepted.

PROFESSIONAL DEVELOPMENT COURSES

Course proposals are solicited from individuals interested in teaching a professional development course on design, manufacturing processes and materials. Proposals, including course descriptions, must be submitted by **August 14, 2015**. Final PowerPoint presentations must be submitted by **December 11, 2015**. Travel expenses and honorariums are offered to professional development instructors.

For [more information](#) about conference participation, please contact Conference Director [Jasbir Bath](#), or [Toya Richardson](#).

For [more information](#) on professional development courses, contact [Anne Marie Mulvihill](#), or [Andrea Pinc](#)

NEWS FROM THE JPCA

The JPCA Show this month in Tokyo showed an increase in the number of visitors as well as the number of exhibitors

Number of visitors 2015

Total	day of week		Number of visitors	
Day 1 June 3	Wednesday		38,070 (36,466)	38,070 (36,466)
Day 2 June 4	Thursday		42,026 (39,361)	80,096 (75,827)
Day 3 June 5	Friday		43,218 (43,393)	123,314 (119,220)

* () is the number of the previous year.